

FH3090D

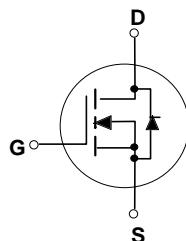
N-Channel Trench Power MOSFET

Features

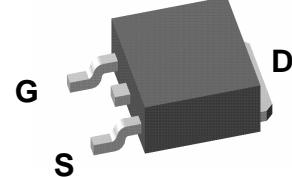
- 30V,90A
- $R_{DS(ON)}=3.6\text{m}\Omega$ (Typ.) @ $V_{GS}=10\text{V}$
- $R_{DS(ON)}=5.0\text{m}\Omega$ (Typ.) @ $V_{GS}=4.5\text{V}$
- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge

Application

- Load Switch
- PWM Application
- Power management



TO-252



Schematic diagram

Marking and pin assignment

TO-252 top view

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_c = 25^\circ\text{C}$	90	A
		$T_c = 100^\circ\text{C}$	58	A
I_{DM}	Pulsed Drain Current ^{note1}		360	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		250	mJ
P_D	Power Dissipation	$T_c = 25^\circ\text{C}$	90	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.67	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	$^\circ\text{C}$

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu\text{A}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V,$	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10V, I_D=30A$	-	3.6	4.8	$\text{m}\Omega$
		$V_{GS}=4.5V, I_D=20A$	-	5	7.3	
g_{FS}	Forward Transconductance	$V_{DS}=5V, I_D=15A$	-	28	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V,$ $f=1.0\text{MHz}$	-	1950	-	pF
C_{oss}	Output Capacitance		-	320	-	pF
C_{rss}	Reverse Transfer Capacitance		-	240	-	pF
Q_g	Total Gate Charge	$V_{DS}=25V, I_D=20A,$ $V_{GS}=10V$	-	42	-	nC
Q_{gs}	Gate-Source Charge		-	4	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	14	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15V,$ $R_i=0.75\Omega, R_{GEN}=3\Omega,$ $V_{GS}=10V$	-	13	-	ns
t_r	Turn-on Rise Time		-	36	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	43	-	ns
t_f	Turn-off Fall Time		-	16	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	90	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	360	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_s=30A$	-	-	1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F=20A, dI/dt=100A/\mu\text{s}$	-	16	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	5	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}, VDD=30V, VG=10V, L=0.5\text{mH}, RG=25\Omega$

Typical Performance Characteristics

Figure 1: Output Characteristics

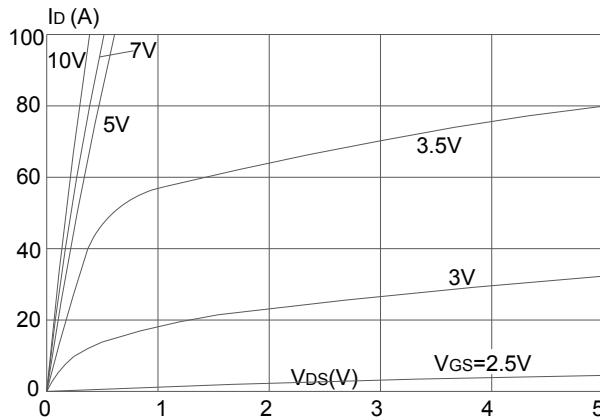


Figure 3: On-resistance vs. Drain Current

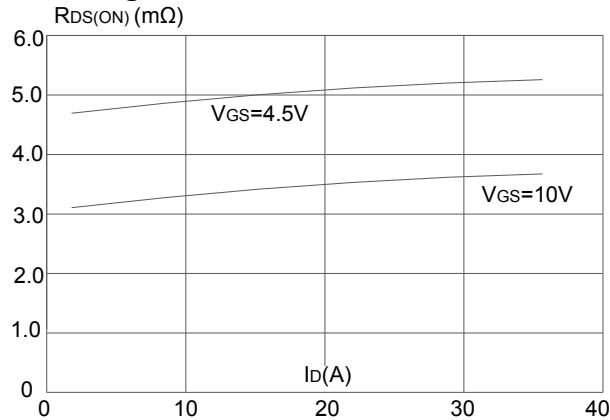


Figure 5: Gate Charge Characteristics

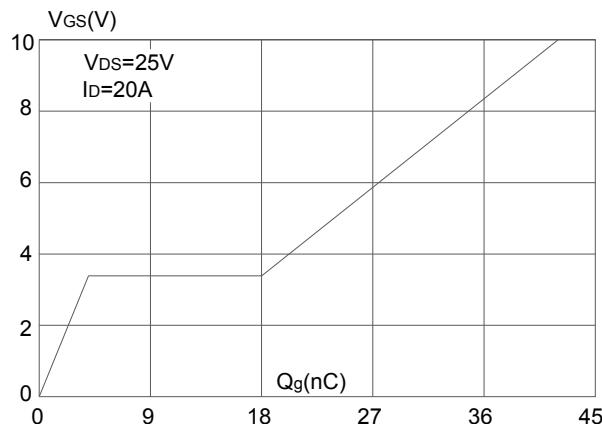


Figure 2: Typical Transfer Characteristics

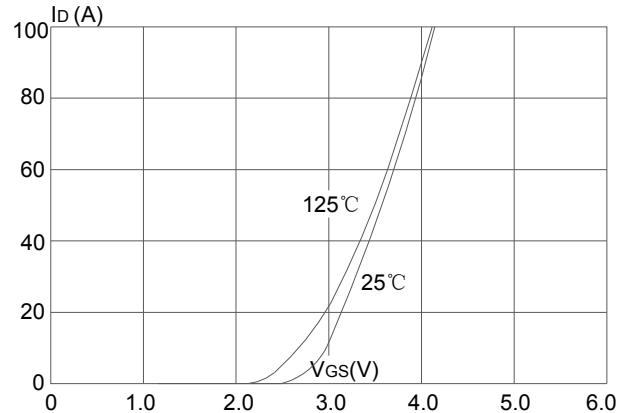


Figure 4: Body Diode Characteristics

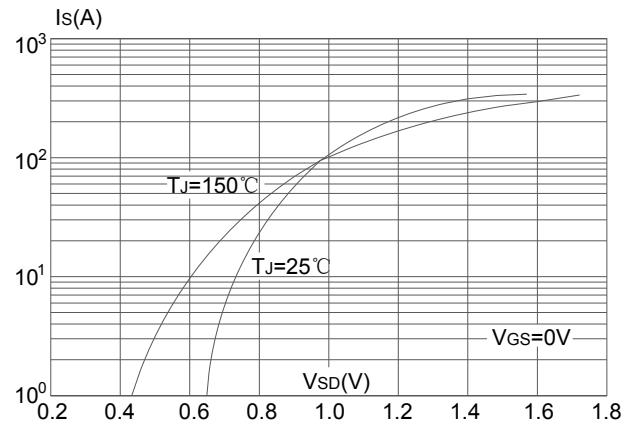


Figure 6: Capacitance Characteristics

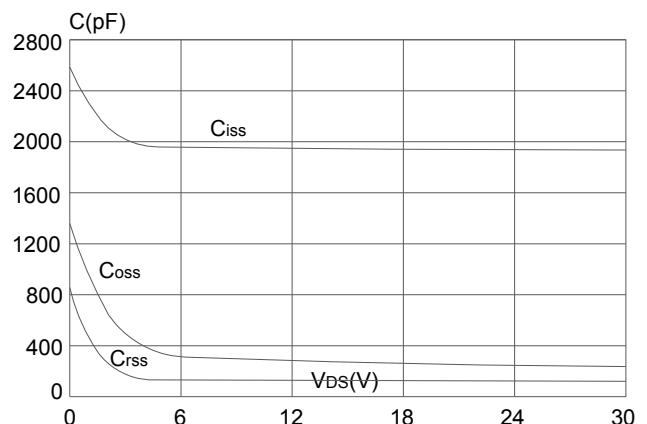


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

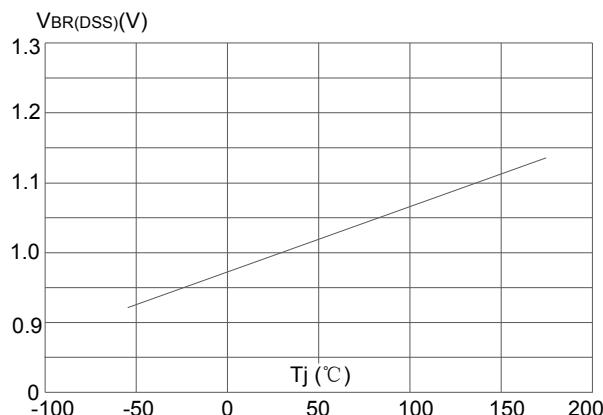


Figure 9: Maximum Safe Operating Area

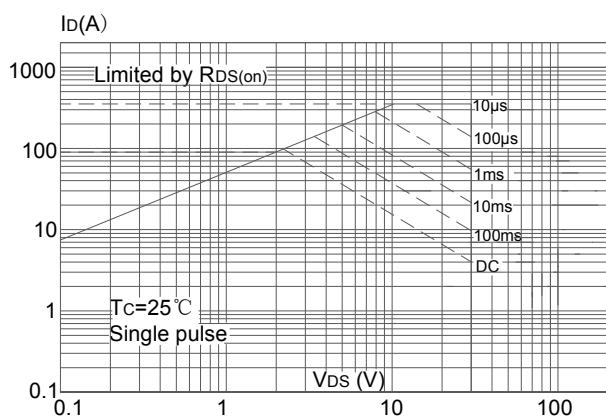


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case (TO-252)

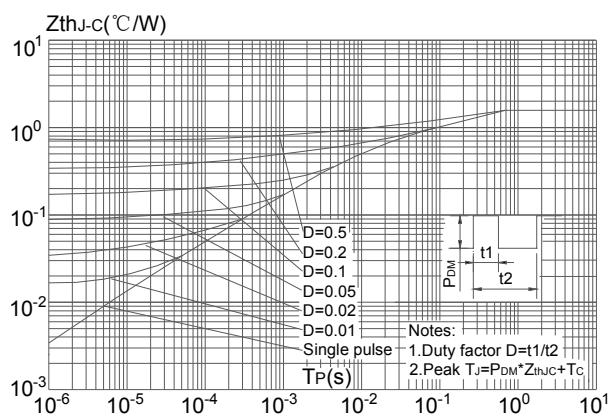


Figure 8: Normalized on Resistance vs. Junction Temperature

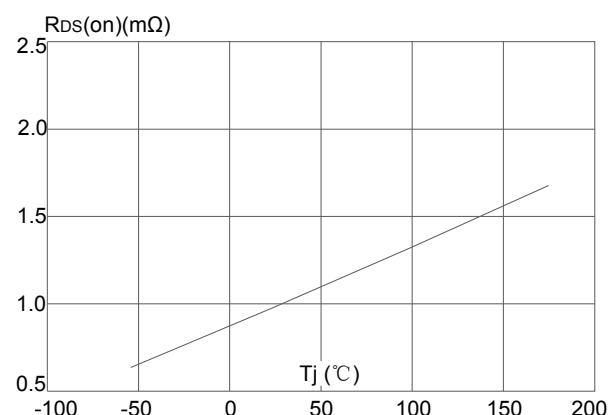
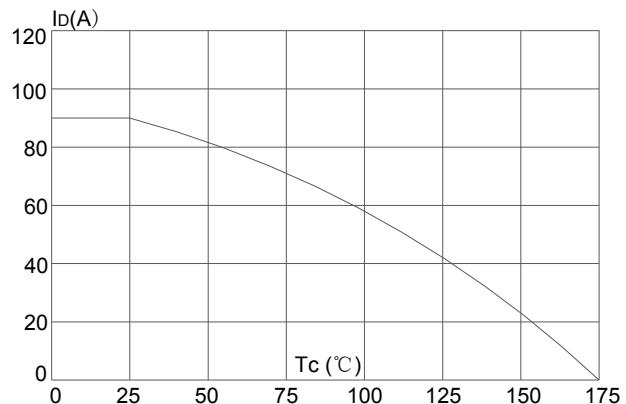


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



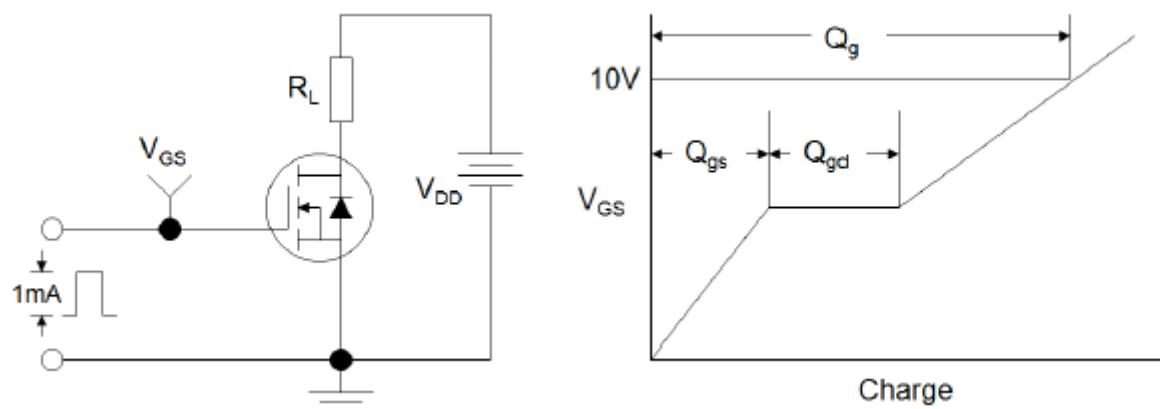


Figure 1: Gate Charge Test Circuit & Waveform

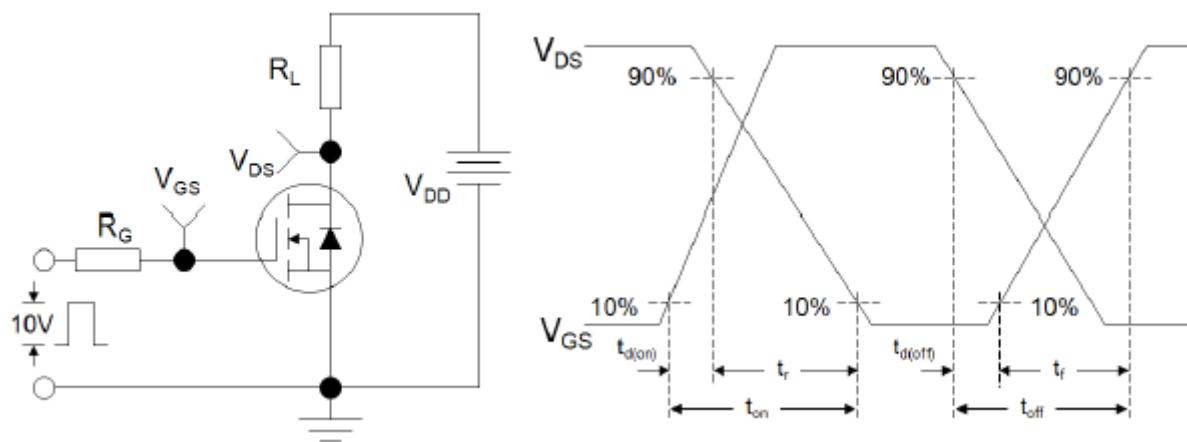


Figure 2: Resistive Switching Test Circuit & Waveforms

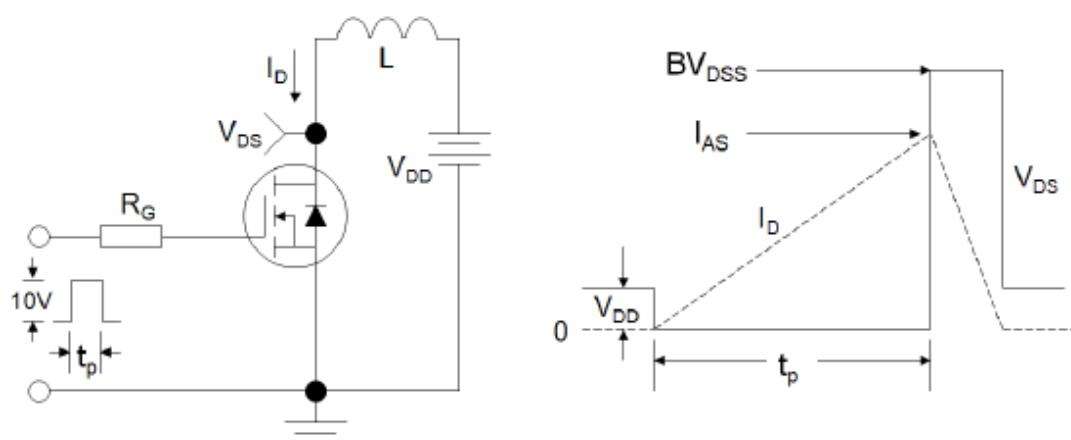
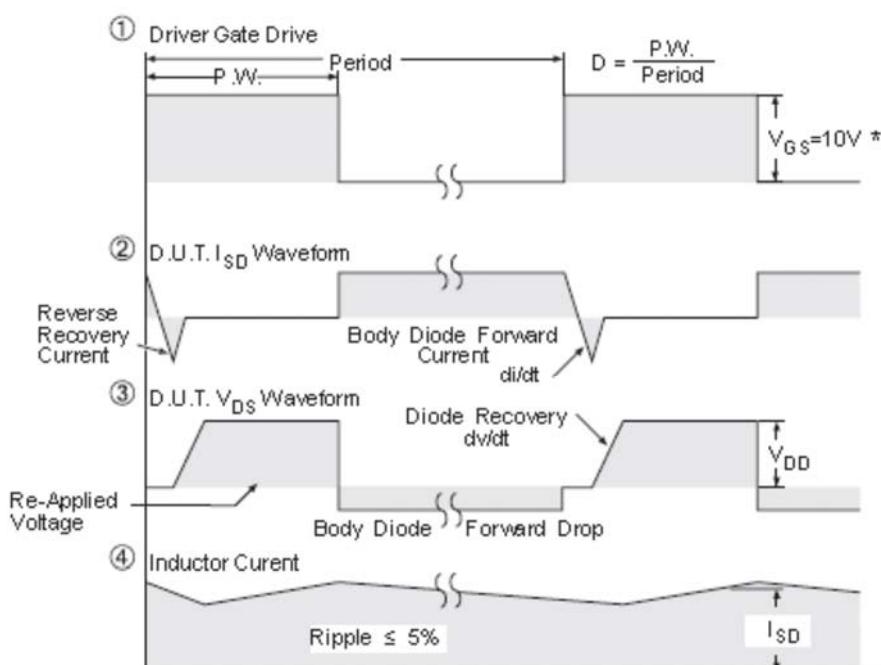
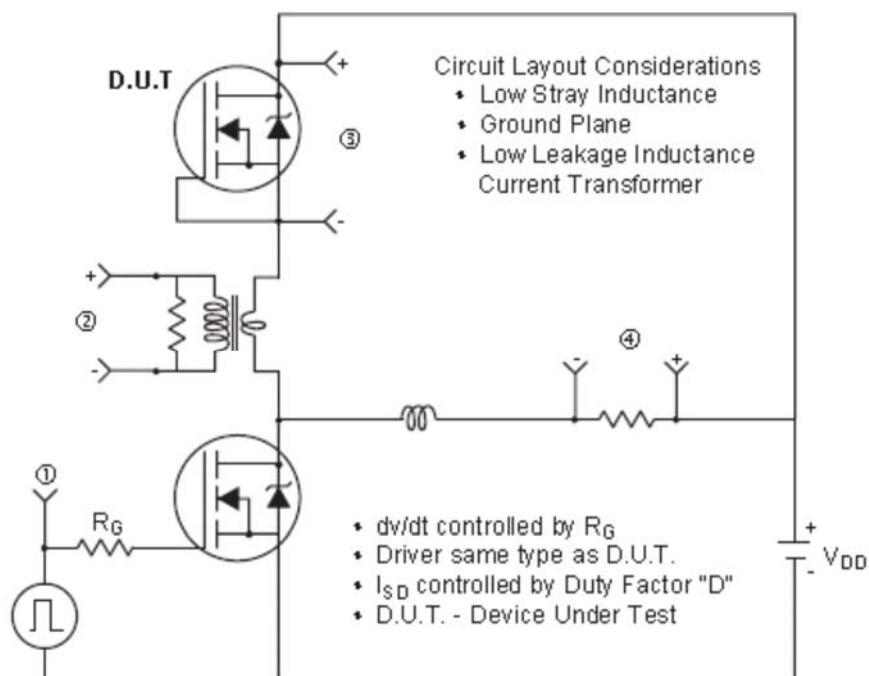


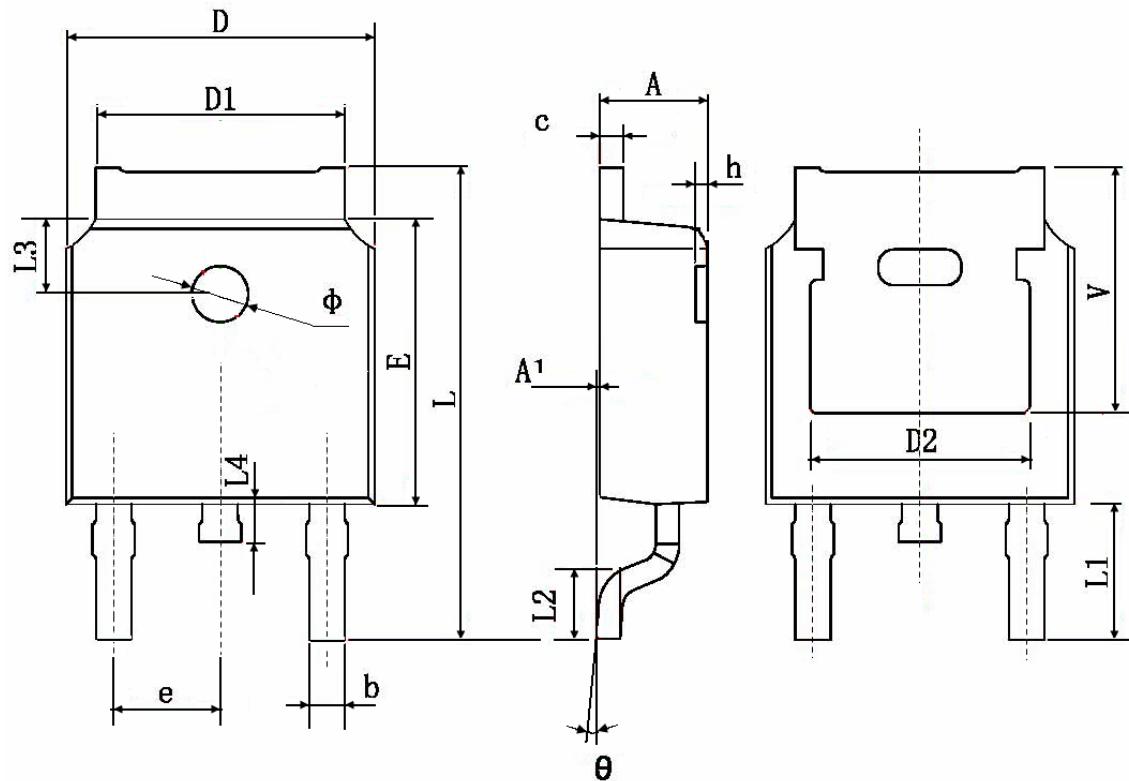
Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms



* $V_{GS} = 5V$ for Logic Level Devices

Figure 4:Peak Diode Recovery dv/dt Test Circuit & Waveforms (For N-channel)

Package Information : TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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